

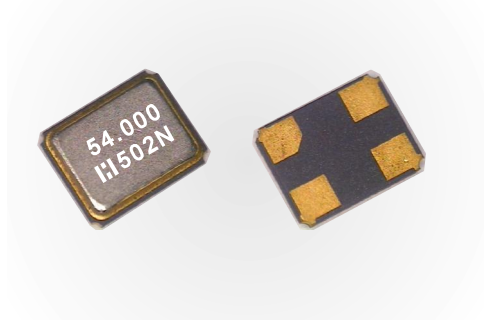


**THE DATASHEET OF
E3SB27E00000DE**





• E3SB Series 3.2*2.5 Seam Sealing Crystal



FEATURES

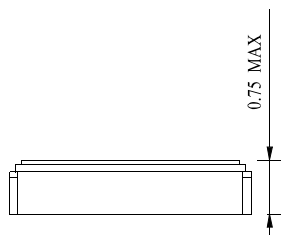
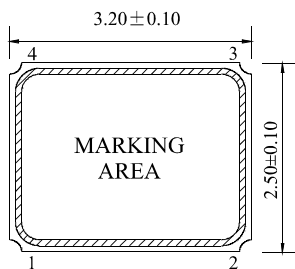
- Compact and thin (3.2X2.5X0.75mm max.)
- Excellent electrical performance, ideal for OA (office automation), AV (audiovisual), Bluetooth and Wireless LAN applications
- Excellent heat resistance and shock resistance.
- Lead-free. Meets the requirements for re-flow profiling using lead-free solder

Electrical Specifications

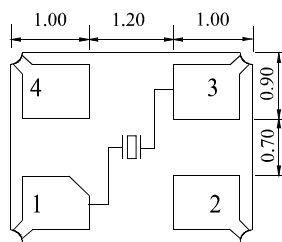
Item	Type	E3SB				
		10 to 11.999MHz	12 to 19.999MHz	20 to 23.999MHz	24 to 62.500MHz	60 to 114.285MHz
Frequency Range	F0	10 to 11.999MHz	12 to 19.999MHz	20 to 23.999MHz	24 to 62.500MHz	60 to 114.285MHz
Mode of Vibration		Fundamental				3RD
Load Capacitance	CL	6 to 20pF				
Frequency Tolerance	$\Delta F/F0$	$\pm 10\text{ppm}, \pm 15\text{ppm}, \pm 30\text{ppm}(\text{At } 25^\circ\text{C})$				
Equivalent Series Resistance	ESR	150 Ω max.	100 Ω max.	70 Ω max.	50 Ω max.	100 Ω max.
Temperature Stability	TC	$\pm 10\text{ppm}, \pm 15\text{ppm}, \pm 30\text{ppm}(\text{Refer to } 25^\circ\text{C})$				
Operating Temperature Range	T _{OPR}	-20~+70°C, -30~+85°C Option				
Storage Temperature Range	T _{STG}	-55~+125°C				
Shunt Capacitance	C0	3pF max.				
Insulator Resistance	IR	500M Ω min. (At 100VDC)				
Drive Level	DL	100 μ W (200 μ W max.)				
Aging	Fa	$\pm 2\text{ppm}$ max. (At 25°C, First year)				
Packing Unit		3000pcs/reel				

**Please contact us for inquiries regarding other Specifications

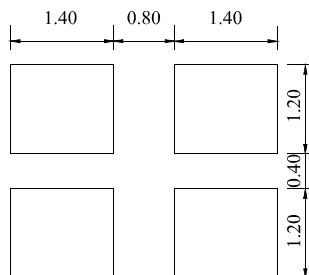
Mechanical Dimensions(mm)



Top View





Recommended Solder Pattern



Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View E3SB27E00000DE on WIN SOURCE](#)
-  [Hosonic Electronic Co., Ltd Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management